

January 2014

# **FDMC7660S**

# N-Channel Power Trench<sup>®</sup> SyncFET<sup>TM</sup> 30 V, 20 A, 2.2 m $\Omega$

### **Features**

- Max  $r_{DS(on)} = 2.2 \text{ m}\Omega$  at  $V_{GS} = 10 \text{ V}$ ,  $I_D = 20 \text{ A}$
- Max  $r_{DS(on)}$  = 2.95 m $\Omega$  at  $V_{GS}$  = 4.5 V,  $I_D$  = 18 A
- High performance technology for extremely low r<sub>DS(on)</sub>
- Termination is Lead-free and RoHS Compliant

# **General Description**

The FDMC7660S has been designed to minimize losses in power conversion applications. Advancements in both silicon and package technologies have been combined to offer the lowest  $r_{DS(on)}$  while maintaining excellent switching performance. This device has the added benefit of an efficient monolithic Schottky body diode.

## **Applications**

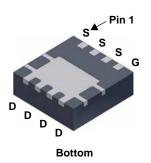
- Synchronous Rectifier for DC/DC Converters
- Notebook Vcore/GPU low side switch
- Networking Point of Load low side switch
- Telecom secondary side rectification

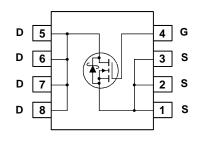




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# **MOSFET Maximum Ratings** $T_A = 25$ °C unless otherwise noted

Symbol	Parameter			Ratings	Units
$V_{DS}$	Drain to Source Voltage			30	V
$V_{GS}$	Gate to Source Voltage		(Note 4)	±20	V
	Drain Current -Continuous (Package limited)	T <sub>C</sub> = 25 °C		40	
	-Continuous (Silicon limited)	T <sub>C</sub> = 25 °C		100	A
<sup>I</sup> D	-Continuous	T <sub>A</sub> = 25 °C	(Note 1a)	20	- A
	-Pulsed			200	
E <sub>AS</sub>	Single Pulse Avalanche Energy	Single Pulse Avalanche Energy (Note 3)		128	mJ
В	Power Dissipation			41	W
$P_{D}$	Power Dissipation		(Note 1a)	2.3	VV
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature R	ange		-55 to +150	°C

### **Thermal Characteristics**

$R_{\theta JC}$	Thermal Resistance, Junction to Case		3	°C/W
R <sub>e,IA</sub>	Thermal Resistance, Junction to Ambient	(Note 1a)	53	C/VV

# **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMC7660S	FDMC7660S	Power 33 13 "		12 mm	3000 units

# **Electrical Characteristics** $T_J = 25$ °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	acteristics					
$BV_DSS$	Drain to Source Breakdown Voltage	$I_D = 1 \text{ mA}, V_{GS} = 0 \text{ V}$	30			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 1 mA, referenced to 25 °C		13		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 24 V, V <sub>GS</sub> = 0 V			500	μΑ
$I_{GSS}$	Gate to Source Leakage Current	$V_{GS} = 20 \text{ V}, V_{DS} = 0 \text{ V}$			100	nA

### **On Characteristics**

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}$ , $I_D = 1 \text{ mA}$	1.2	1.6	2.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I <sub>D</sub> = 1 mA, referenced to 25 °C		-3		mV/°C
		$V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$		1.7	2.2	
r <sub>DS(on)</sub>	Static Drain to Source On Resistance	$V_{GS} = 4.5 \text{ V}, I_D = 18 \text{ A}$		2.5	2.95	mΩ
, ,		$V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}, T_J = 125 \text{ °C}$		2.2	3.1	
9 <sub>FS</sub>	Forward Transconductance	$V_{DD} = 5 \text{ V}, I_{D} = 20 \text{ A}$		129		S

# **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V 45.V.V 0.V		3250	4325	pF
C <sub>oss</sub>	Output Capacitance	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1  MHz		1260	1680	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 1 1011 12		105	160	pF
$R_{q}$	Gate Resistance		0.1	0.8	1.6	Ω

# **Switching Characteristics**

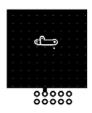
t <sub>d(on)</sub>	Turn-On Delay Time			14	25	ns
t <sub>r</sub>	Rise Time	V <sub>DD</sub> = 15 V, I <sub>D</sub> = 20 A,		5	10	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$		34	54	ns
t <sub>f</sub>	Fall Time			3.9	10	ns
0	Total Gate Charge	V <sub>GS</sub> = 0 V to 10 V		47	66	nC
$Q_{g(TOT)}$	Total Gate Charge	$V_{GS} = 0 \text{ V to } 4.5 \text{ V}$ $V_{DD} = 15 \text{ V}$	<b>V</b>	21	29	nC
$Q_{gs}$	Total Gate Charge	I <sub>D</sub> = 20 A		9.5		nC
$Q_{gd}$	Gate to Drain "Miller" Charge			5		nC

# **Drain-Source Diode Characteristics**

V	V <sub>CD</sub> Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 20 \text{ A}$	(Note 2)	8.0	1.2	V
V SD		$V_{GS} = 0 \text{ V}, I_{S} = 1.9 \text{ A}$	(Note 2)	0.4	0.7	<b>v</b>
t <sub>rr</sub>	Reverse Recovery Time	-I <sub>F</sub> = 20 A, di/dt = 300 A/μs		31	50	ns
Q <sub>rr</sub>	Reverse Recovery Charge			39	62	nC

### NOTES

<sup>1.</sup> R<sub>0,1A</sub> is determined with the device mounted on a 1in<sup>2</sup> pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R<sub>0,1C</sub> is guaranteed by design while R<sub>0,1C</sub> is determined by the user's board design.



a. 53°C/W when mounted on a 1 in<sup>2</sup> pad of 2 oz copper



b. 125°C/W when mounted on a minimum pad of 2 oz copper

- 2. Pulse Test: Pulse Width < 300  $\mu\text{s},$  Duty cycle < 2.0 %.
- 3. Starting  $T_J = 25^{\circ}C$ ; N-ch: L = 1 mH,  $I_{AS} = 16$  A,  $V_{DD} = 27$  V,  $V_{GS} = 10$  V.
- 4. As an N-ch device, the negative Vgs rating is for low duty cycle pulse ocurrence only. No continuous rating is implied.

# Typical Characteristics T<sub>J</sub> = 25 °C unless otherwise noted

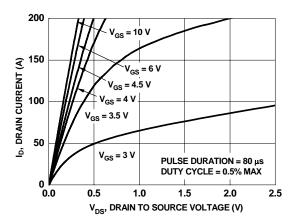


Figure 1. On-Region Characteristics

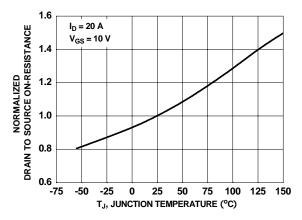


Figure 3. Normalized On-Resistance vs Junction Temperature

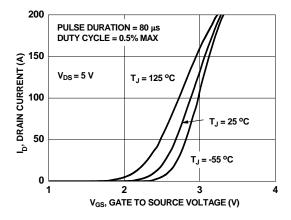


Figure 5. Transfer Characteristics

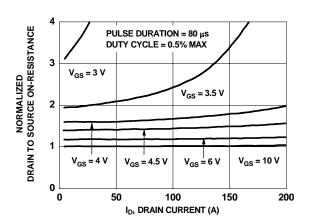


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

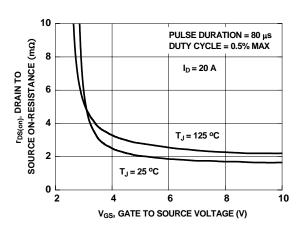


Figure 4. On-Resistance vs Gate to Source Voltage

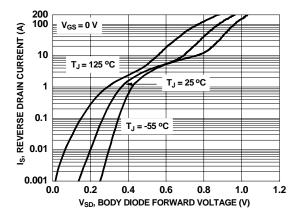


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

# **Typical Characteristics** $T_J = 25$ °C unless otherwise noted

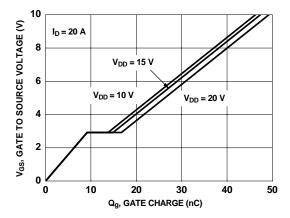


Figure 7. Gate Charge Characteristics

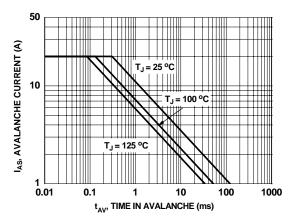


Figure 9. Unclamped Inductive Switching Capability

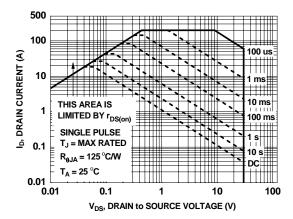


Figure 11. Forward Bias Safe Operating Area

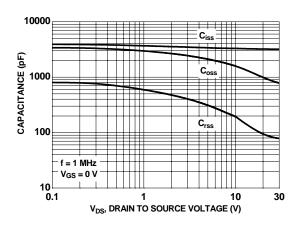


Figure 8. Capacitance vs Drain to Source Voltage

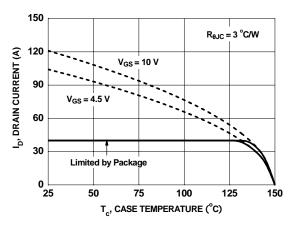


Figure 10. Maximum Continuous Drain Current vs Ambient Temperature

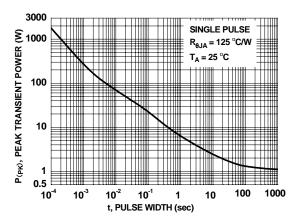


Figure 12. Single Pulse Maximum Power Dissipation

# Typical Characteristics $T_J = 25$ °C unless otherwise noted

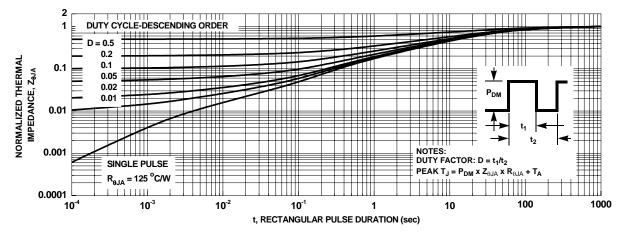


Figure 13. Junction-to-Ambient Transient Thermal Response Curve

# Typical Characteristics (continued)

# SyncFET Schottky body diode Characteristics

Fairchild's SyncFET process embeds a Schottky diode in parallel with PowerTrench MOSFET. This diode exhibits similar characteristics to a discrete external Schottky diode in parallel with a MOSFET. Figure 27 shows the reverse recovery characteristic of the FDMC7660S.

Schottky barrier diodes exhibit significant leakage at high temperature and high reverse voltage. This will increase the power in the device.

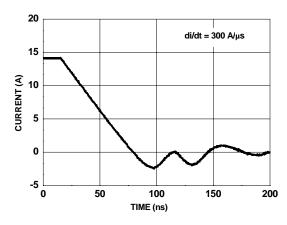


Figure 14. FDMC7660S SyncFET body diode reverse recovery characteristic

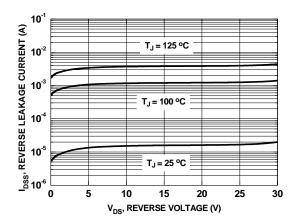


Figure 15. SyncFET body diode reverse leakage versus drain-source voltage

# **Dimensional Outline and Pad Layout** $-3.30\pm0.10-$ 2.37 MIN PKG SYM Œ -(0.45) 8 5 2.15 MIN (0.40)PKG Q-PKGQ $3.30\pm0.10$ (0.65) $\bigcirc$ 0.70 MIN 4 -0.42 MIN 0.65 SEE DETAIL A -1.95 LAND PATTERN RECOMMENDATION 1.95 0.65 0.32±0.05-◆ 0.10 C A B $-0.40\pm0.10$ (0.20)PKGQ $2.00\pm0.10$

NOTES: UNLESS OTHERWISE SPECIFIED

- A) PACKAGE STANDARD REFERENCE:

  JEDEC MO-240, ISSUE A, VAR. BA,

  DATED OCTOBER 2002.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
- D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- E) DRAWING FILE NAME: PQFN08BREV1

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 $(0.39)^{\frac{1}{2}}$ 

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